DIP HERMETIC NETWORK SERIES

Dual-In-Line Hermetic Resistor Networks

FEATURES

- **Temperature Coefficient of Resistance**
  (-55 °C to 125 °C, 25 °C as reference.): ± 2.0 ppm/ °C
- **TCR Tracking**
  (-55 °C to 125 °C, 25 °C as reference.):
  Without selection: All within 5 ppm/°C
  With selection: All within 0.5ppm/°C
- **Resistance Range** (per element): 5Ω to 80 KΩ
- **Tolerance**: Absolute: to 0.005%
  Match: to 0.0005%
- **Load Life Stability**: ± 0.015% Max. ΔR under full rated power, @ 70 C for 2000 hours.
- **Shelf Life Stability**: 5 ppm/year. Max. ΔR hermetically sealed.
- **Rise Time**: 1ns, effectively no ringing.

For complete datasheet on resistive elements please go to: http://www.texascomponents.com/pdf/vrhc.pdf

	Model	Number of Pins	Chip Capacity		Power Rating @70°C	Package Type	Dimensions In Inches (see Figure 1)
			V5x5	V15x5			
	**1442**	8	12	4	0.4W	Side Brazed DIP Ceramic Package	L: 0.520 ±0.020 W: 0.295±0.010 B: 0.054 LL: 0.125
	**1445**	14	30	10	1.2W	Side Brazed DIP Ceramic Package	L: 0.740±0.045 W: 0.270+0.035/-0.030 B: 0.046 LL: 0.135+0.015/-0.010
	**1446**	16	36	12	1.4W	Side Brazed DIP Ceramic Package	L: 0.780±0.030 W: 0.290±0.008 B: 0.040 to 0.070 LL: 0.135+0.015/-0.010
	**1457**	18	80	25	1.8W	"L" Brazed Dip Ceramic Package (Maintains 0.300" pin Spacing)	L: 0.990±0.030 W: 0.490±0.020 B: 0.046 LL: 0.125
	**1460**	20	221	73	2.4W	20 pin Side Brazed 1"x1" DIP Ceramic Package	L: 1.00±0.020 W: 0.900±0.010 B:0.050 LL: 0.125

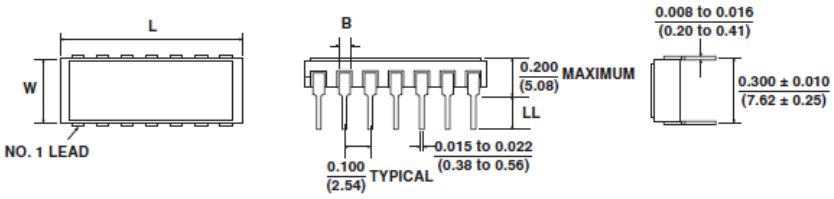

Figure 1

Construction	Hermeticity
Ceramic Package: 94% Alumina (AL_2O_3) **Lid**: Gold Plated Kovar **Leads**: Alloy 43 (Iron Nickel) with 50μ" gold plating, MIL-Std-1276, Type G-22-A1	**Gross Leak**: No Bubbles, MIL-Std-202, Method 112, Test Condition D

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